



Click [here](#) for the 3D model.

Dimensions	
Chip Size	2225
L	5.588mm +/-0.381mm (0.22 in +/-0.015 in)
W	6.35mm +/-0.381mm (0.25 in +/-0.015 in)
T	1.778mm MAX (0.07 in MAX)

Packaging Specifications	
Packaging	Waffle
Packaging Quantity	25000

General Information	
Series	SMD Mil PRF123
Style	SMD Chip
Description	SMD Chip, Ultra Stable
RoHS	No
Prop 65	<b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> .
SCIP Number	646e40c8-ce81-456e-b9ed-50112f3d27a5
Termination	Nickel
Failure Rate	N/A
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3900 pF
Capacitance Tolerance	1%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vms
Dissipation Factor	2.5%
Insulation Resistance	100 GOhms

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)